

Title (en)

MOBILE DEVICE, EXPOSURE DEVICE, EXPOSURE METHOD, MICRO-MOTION BODY, AND DEVICE MANUFACTURING METHOD

Title (de)

MOBILE EINRICHTUNG, BELICHTUNGSEINRICHTUNG, BELICHTUNGSVERFAHREN, MIKROBEWEGUNGSKÖRPER UND  
BAUELEMENTEHERSTELLUNGSVERFAHREN

Title (fr)

DISPOSITIF MOBILE, DISPOSITIF D'EXPOSITION, PROCEDE D'EXPOSITION, CORPS A DEPLACEMENT MICROMETRIQUE ET PROCEDE  
DE FABRICATION DE DISPOSITIFS

Publication

**EP 2006884 A2 20081224 (EN)**

Application

**EP 07715038 A 20070228**

Priority

- JP 2007053723 W 20070228
- JP 2006095982 A 20060330

Abstract (en)

Power-transmitting, waste-heat frames (24A, 24B) can continually absorb heat radiated from wafer stages (WST1, WST2), and therefore it becomes possible to suppress adverse influence on exposure accuracy due to the heat generated at the wafer stages (WST1, WST2). In this case, unlike the conventional method, it is not necessary to connect a conduit (tube) for supplying coolant to the wafer stages (WST1, WST2) from the outside, and accordingly declines in movement accuracy of the wafer stages (WST1, WST2) due to tension of such a conduit can be prevented. Also from this standpoint, the exposure accuracy can be maintained at high accuracy.

IPC 8 full level

**H01L 21/027** (2006.01); **G03F 7/20** (2006.01); **H01L 21/68** (2006.01)

CPC (source: EP KR US)

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EP 2006884 A9 20090715; JP 2013149996 A 20130801; JP 5257845 B2 20130807; JP 5725059 B2 20150527; JP WO2007113955 A1 20090813;  
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JP 2008508463 A 20070228; JP 2013046987 A 20130308; KR 20087024702 A 20081009; KR 20147005802 A 20070228;  
TW 96105249 A 20070213